Power Packages

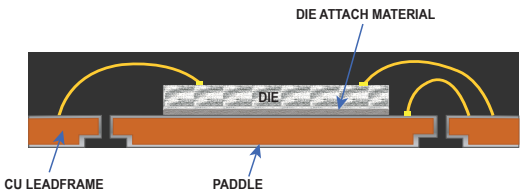
ATROX® Pressureless Hybrid Silver Sintered Die Attach

ATROX® provides a high reliability sintered die attach solution to address the most stringent power and connectivity requirements

- High thermal die attach paste and film
- Standard die attach equipment and process
- High yield and high throughput
- High reliability copper clip attach

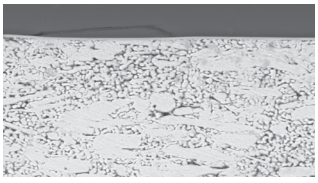
ATROX® Hybrid Silver Sintering Paste for Exposed Pad Power Packages

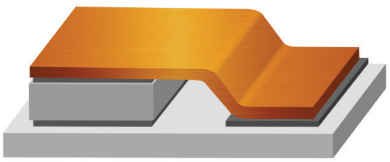
ATROX® 800HT Series is a thermosetting conductive die attach adhesive with high thermal conductivity (>70 W/m-K) designed for presureless assembly of high power exposed pad semiconductor packages. It has excellent adhesive strength to NiPdAu, Ag and roughened leadframes, low out gassing which minimizes oven contamination and is ideal for excellent MSL performance.



ATROX® Die Attach and Clip Attach Process

- Designed for packages requiring excellent heat dissipation
- Low modulus materials for large die sizes
- Superior adhesion to copper clip surfaces
- No resin bleed out and void free processing
- Printable and dispensable solutions available
- Proven HVM solutions for OEM and OSAT's

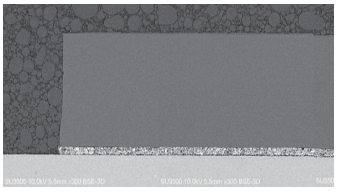


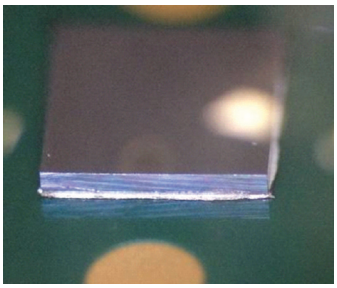


ATROX® High Thermal Conductive Film

ATROX® CF200-1D is an electrically conductive die attach film with thermal conductivity of >20 W/m-K. It offers excellent bond-ability to a variety of lead-frame surfaces and die sizes.

The film has excellent bond line control with no die tilting resulting in a high yield assembly process. The film also offers superior reliability performance in a variety of packages.

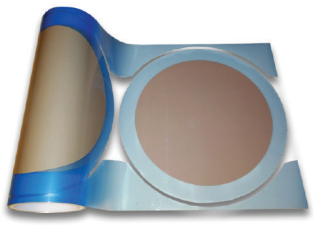




- Industry's leading high thermal film solution
- Thermal conductivity >20W/m-K
- Controlled fillet with no RBO
- Mild process conditions
- Low ionic content
- Standard thickness of 15um in 8" and 12" sizes
- Proven solution for MSL1 and high reliability

Summary for Paste and Film

- ATROX® high thermal products offer superior reliability and performance
- Rapid heat dissipation enables higher efficiencies and operating temperatures
- Key enabler for package shrinkage and higher power density packaging
- Excellent workability and processing
- Drop in process for OEM and subcons
- Proven performance across a range of exposed pad power packages



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